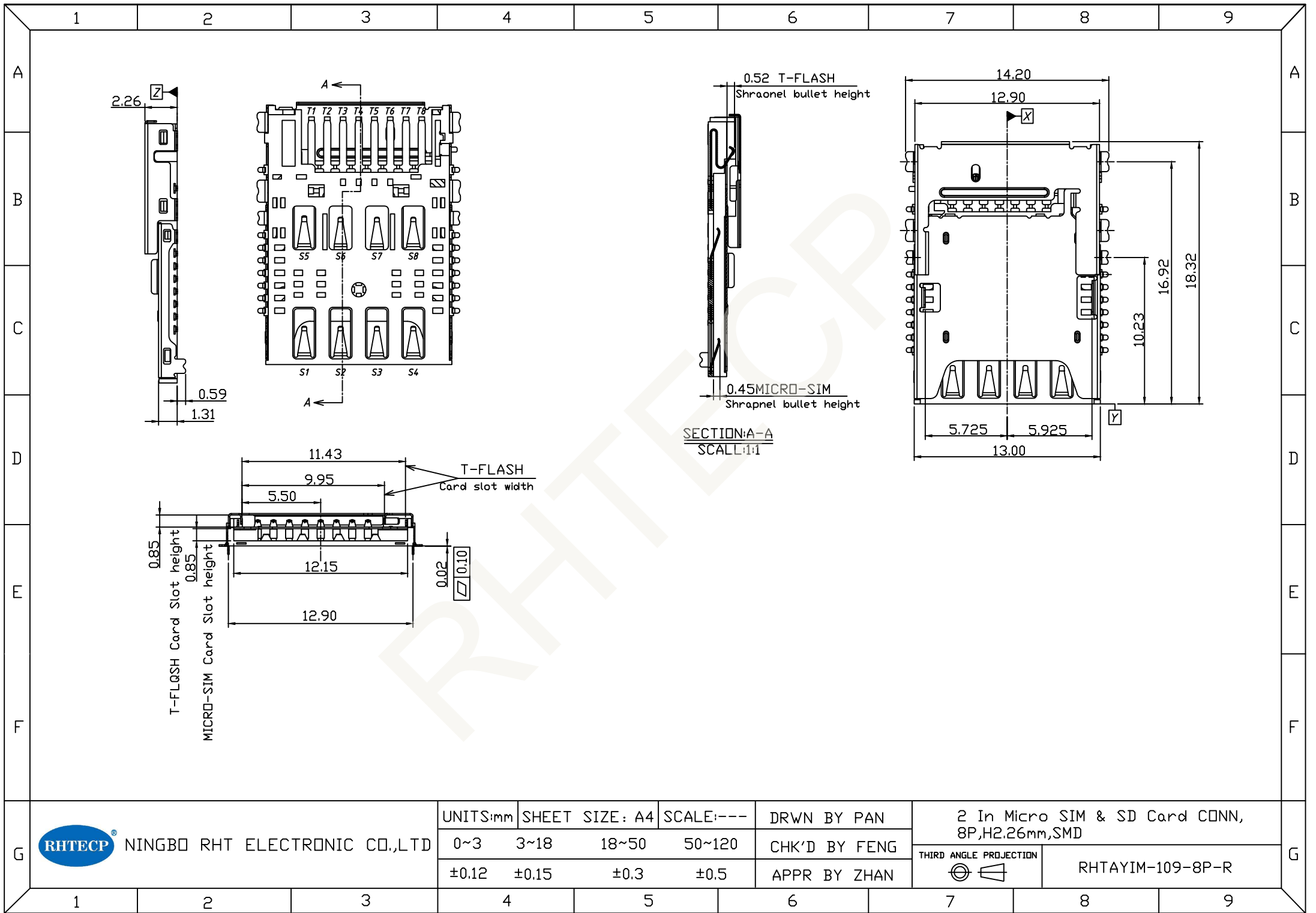
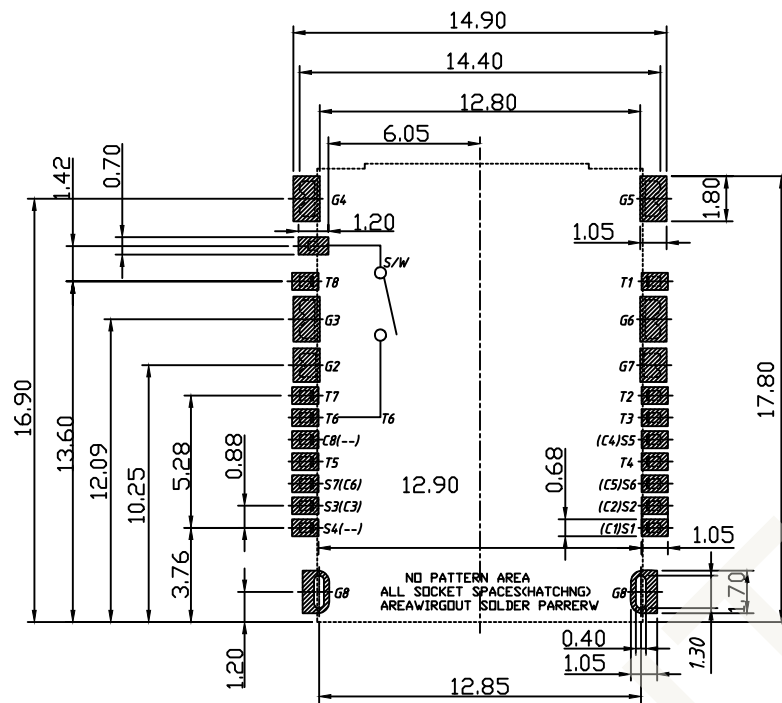
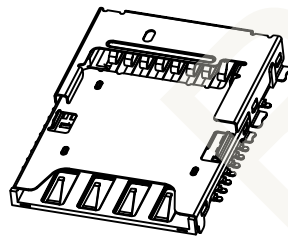






RECOMMENDED PCB LAYOUT
TOLERANCE ± 0.05



Material:

Insulator: High Temp Thermoplastic, UL 94 V-0, Black.
Terminal: Copper Alloy, Gold plating in contact area 1u", Soldering Area gilding 1u"

Upper Shell: Stainless Steel, Plate Nickel 50u"

Down Shell: SUS304 R-1/2H T=0.10mm, Plate Nickel 50u"

Electrical:

Insertion Force 1kgf Max.

Withdrawal Force 0.1kgf Min.

Durability: SIM 5000 Cycles, T 10000 Cycles.

Contact Resistance: Before testing 80m Ω Max, After testing 120m Ω Max.

Insulation Resistance: 1000M Ω

Withstanding Voltage: 500V AC For 1 minute.

MICRO SIM CARD PIN-MAP

8P	6P	DESCRIPTION
S1	C1	VCC(SUPPLY)
S2	C2	RST(RESET)
S3	C3	CLK(CLOCK)
S4	--	RESERVED
S5	C4	GND
S6	C5	VPP(PROGRAMV)
S7	C6	I/O
S8	--	RESERVED
G1-G8		GND

MICRO SIM CARD PIN-MAP

PIN NO.	DESCRIPTION
T1	DAT2
T2	CD/DAT3 ²
T3	CMD
T4	VDD
T5	CLK
T6	VSS(GND)
T7	DAT0
T8	DAT1